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Patent

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Attorney Docket No. MTI-31608

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant

TECHNOLOGY, INC.,  
Tan, Hock Chuan, et al.

Serial No.

10/068,159

Filing Date

: February 5, 2002

For

: Stacked Die in Die BGA Package

*2/ Power of  
Attorneys  
By Assignee*

Assistant Commissioner for Patents

Washington, D.C. 20231

**POWER OF ATTORNEY BY ASSIGNEE  
AND CERTIFICATE UNDER 37 CFR § 3.73(b)**

Sir:

MICRON TECHNOLOGY, INC., assignee of the entire right, title and interest by assignment from the inventor(s) in the above-identified application, hereby appoints the following attorneys and agents:

Gary R. Plotcher, Reg. No. 27830

Kristine M. Strodthoff, Reg. No. 34259

Alan E. Wagner, Reg. No. 45188

Thomas J. Pienkos, Reg. No. 46992

Alexander R. Kuszewski, Reg. No. 41920

Elisabeth T. Bridge, Reg. No. 37523

Charles B. Brantley, II, Reg. No. 38086

Michael L. Lynch, Reg. No. 30871

William H. Dietrich, Reg. No. 48359

as its attorneys with full power of substitution to prosecute this application and all applications claiming filing date priority therefrom and to transact all business in the U.S. Patent and Trademark Office in connection therewith.

**The above-identified assignee hereby elects, pursuant to 37 CFR §3.71, to conduct the prosecution of the above-identified patent application to the exclusion of the inventor(s).**

A chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee is shown:

- In an assignment recorded in the U.S. Patent and Trademark Office at Reel \_\_\_, Frame \_\_\_\_.
- In an assignment filed herewith for recordation, a true copy of which is attached hereto.

The undersigned has reviewed the above-identified assignment and, to the best of his knowledge and belief, title is in the above-identified assignee.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the above-identified assignee, and to take the action set further herein on its behalf.

Please direct all communications regarding the above-identified application to:

Kristine M. Strothoff  
Whyte Hirschboeck Dudek S.C.  
111 E. Wisconsin Ave., Suite 2100  
Milwaukee, WI 53202  
phone: (414) 273-2100  
fax: (414) 223-5000

Respectfully submitted,

MICRON TECHNOLOGY, INC.

Dated: 02/20/02

By: Roderic W. Lewis  
Roderic W. Lewis  
Vice President-Legal Affairs,  
General Counsel and Corporate Secretary

MAR 22 2002

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Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE

**STATEMENT UNDER 37 CFR 3.73(b)**

Applicant/Patent Owner: Tan, Hock Chuan et al.

Application No./Patent No.: 10/068,159 Filed/Issue Date: 02/05/02

Entitled: Stacked Die in Die BGA Package

Micron Technology, Inc., a Corporation,

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

- the assignee of the entire right, title, and interest; or
- an assignee of an undivided part interest

in the patent application/patent identified above by virtue of either:

A.  An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the Patent and Trademark Office at Reel       , Frame       , or for which a copy thereof is attached.

OR

B.  A chain of title from the inventor(s) of the patent application/patent identified above, to the current assignee as shown below:

1. From: \_\_\_\_\_ To: \_\_\_\_\_  
The document was recorded in the Patent and Trademark Office at  
Reel       , Frame       , or for which a copy thereof is attached.
2. From: \_\_\_\_\_ To: \_\_\_\_\_  
The document was recorded in the Patent and Trademark Office at  
Reel       , Frame       , or for which a copy thereof is attached.
3. From: \_\_\_\_\_ To: \_\_\_\_\_  
The document was recorded in the Patent and Trademark Office at  
Reel       , Frame       , or for which a copy thereof is attached.

Additional documents in the chain of title are listed on a supplemental sheet.

Copies of assignments or other documents in the chain of title are attached.

[NOTE]: A separate copy (i.e., the original assignment document or a true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the PTO. See MPEP 302-302.8

The undersigned (whose title is supplied below) is empowered to sign this statement on behalf of the assignee.

02/20/02  
Date

Roderic W. Lewis  
Signature

Roderic W. Lewis

Typed or printed name

Vice President-Legal Affairs, General Counsel and  
Corporate Secretary

Title

For:  U.S. and/or  Foreign-Rights  
For:  U.S. Application-or  U.S. Provisional Application  
For:  U.S. Patent For:  PCT Application  
By:  Inventor or  Present-Owner

### ASSIGNMENT OF INVENTION (MULTIPLE INVENTORS)

In consideration of the payment by ASSIGNEE to ASSIGNORS of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

#### ASSIGNORS:

Hock Chuan Tan  
Block 159, Pasir Ris St. 13, #07-09  
Singapore 510159  
Nationality Republic of Singapore

Thiam Chye Lim  
Block 51, Tampines Ave 1  
#10-06, The Tropica Singapore 529771  
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Victor Cher Khng Tan  
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Michael Kian Shing Tan  
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Nationality Republic of Singapore

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Singapore 680106  
Nationality Republic of Singapore

Cheng Poh Pour  
11 Flora Road #03-06, Avila Gardens  
Singapore 509732  
Nationality Republic of Singapore

hereby sells, assigns and transfers to

#### ASSIGNEE:

Micron Technology, Inc.  
Inventor(s) or person(s) or entity(ies) who own the invention

8000 S. Federal Way  
Boise, Idaho 83706-9632  
Address

and the successors, assigns and legal representatives of the ASSIGNEE  
(complete one of the following)

- the entire right, title and interest
- an undivided percent (%) interest for the United States and its territorial possessions
- and in all foreign countries, including all rights to claim priority in and to any and all improvements which are disclosed in the invention entitled:

#### **STACKED DIE IN DIE BGA PACKAGE**

and which is found in (37 C.F.R. § 3.21)

- (a)  U.S. patent application executed on even date herewith
- (b)  U.S. patent application executed on \_\_\_\_\_.
- (c)  U.S. provisional application naming the above inventor(s) for the above-entitled invention  
 Express mail label no.: \_\_\_\_\_

Mailed: \_\_\_\_\_

- To comply with 37 C.F.R. § 3.21 for recordal of this assignment, I, an ASSIGNOR signing below, hereby authorize and request my attorney to insert below the filing date and application number when they become known.
- (d)  U.S. application no. \_\_\_\_\_ filed on \_\_\_\_\_
- (e)  International application no. \_\_\_\_\_ PCT/ filed on \_\_\_\_\_
- (f)  U.S. patent no. \_\_\_\_\_ issued \_\_\_\_\_
- A change of address to which correspondence is to be sent regarding patent maintenance fees is being sent separately.

(check (g), if foreign application(s) is also being assigned)

- (g)  and any legal equivalent thereof in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has

been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this \_\_\_\_\_ day of  
\_\_\_\_\_, 2002.

WARNING: The date of signing must be the same as the date of execution of the application, if item (a) was checked above.

Date: 1/15/02

  
Hock Chuan Tan

Date: 1/15/02

  
Thiam Chye Lim

Date: \_\_\_\_\_

  
Victor Cher Khng Tan

Date: 1/15/02

  
Chee Peng Neo

Date: 1/15/02

  
Michael Kian Shing Tan

Date: 1/15/02

  
Beng Chye Chew

\*\*\*\*\*  
Date: 1/15/02

  
Cheng Poh Pour



been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

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IN WITNESS WHEREOF, I have hereunto set hand and seal this \_\_\_\_\_ day of  
\_\_\_\_\_, 2002.

WARNING: The date of signing must be the same as the date of execution of the application, if item (a) was checked above.

Date: \_\_\_\_\_

Hock Chuan Tan

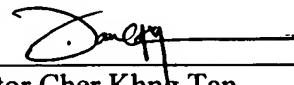
\*\*\*\*\*

Date: \_\_\_\_\_

Thiam Chye Lim

\*\*\*\*\*

Date: 1/22/2002

  
Victor Cher Khng Tan

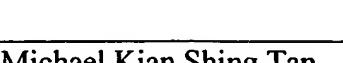
\*\*\*\*\*

Date: \_\_\_\_\_

Chee Peng Neo

\*\*\*\*\*

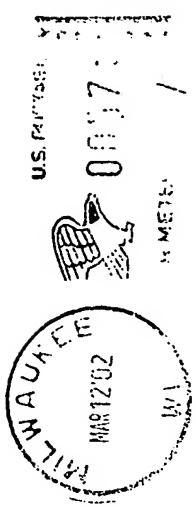
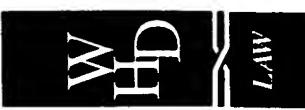
Date: \_\_\_\_\_

  
Michael Kian Shing Tan

\*\*\*\*\*

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Assistant Commissioner for Patents  
Washington, D.C. 20231

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